

APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

Atty. Docket No.: END9-2000-0162-US1 (IEN-10-5533)

Serial No.: To be assigned

10/665104

Applicant: Brodsky

Filing Date: Herewith 9/17/03

Group: 2833

U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
CH	AA	4,988,306	01/29/91	Hopfer, III et al	439	66	05/16/89
CH	AB	5,122,067	06/16/92	Sunne	439	91	05/23/91
CH	AC	5,599,193	02/04/97	Crotzer	439	66	08/23/94
CH	AD	5,650,919	07/22/97	Loh et al	361	779	02/21/96
CH	AE	5,720,630	02/24/98	Richmond et al	439	591	02/26/96
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CH	AG	5,899,757	05/04/99	Neidich et al	439	67	11/03/97
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FOREIGN REFERENCES

AL							
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OTHER DOCUMENTS

CH	AO	IBM Technical Disclosure Bulletin, January, 1993, "Button Contacts for Probe Card Applications", pp. 186-187
CH	AP	IBM Technical Disclosure Bulletin, March, 1991, "Pluggable/Removable Cube of Chips Packaging Method", pp. 459-460
	AQ	
	AR	
	AS	
	AT	

Examiner: Menyamel Date Considered: 4/25/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered.
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